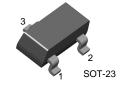


PN100/PN100A/MMBT100/MMBT100A

NPN General Purpose Amplifier

- This device is designed for general purpose amplifier applications at collector currents to 300mA.
- Sourced from process 10.





1. Emitter 2. Base 3. Collector Mark: PN100/PN100A

1. Base 2. Emitter 3. Collector Mark: N1/N1A

Absolute Maximum Ratings* T_C=25°C unless otherwise noted

Symbol	Parameter		Value	Units
V_{CEO}	Collector-Emitter Voltage		45	V
V _{CBO}	Collector-Base Voltage		75	V
V _{EBO}	Emitter-Base Voltage		6.0	V
I _C	Collector current	- Continuous	500	mA
T _J , T _{sta}	Junction and Storage Temperature		-55 ~ + 150	°C

^{*} These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- These ratings are based on a maximum junction temperature of 150 degrees C.
 These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Electrical Characteristics $\ensuremath{\mathsf{T}}_C \!\!=\!\! 25^{\circ}\ensuremath{\mathsf{C}}$ unless otherwise noted

Symbol	Parameter	Test Condition		Min.	Max.	Units
Off Charac	teristics	•		•	•	
BV _{CBO}	Collector-Base Breakdown Voltage	$I_C = 10\mu A, I_E = 0$		75		V
BV _{CEO}	Collector-Emitter Breakdown Voltage *	$I_{C} = 1 \text{mA}, I_{B} = 0$		45		V
BV _{EBO}	Emitter-Base Breakdown Voltage	$I_E = 10\mu A, I_C = 0$		6.0		V
I _{CBO}	Collector-Base Cutoff Current	V _{CB} = 60V			50	nA
I _{CES}	Collector-Emiitter Cutoff Current	V _{CE} = 40V			50	nA
I _{EBO}	Emitter Cutoff Current	V _{EB} = 4V			50	nA
On Charac	teristics	<u> </u>				
h _{FE}	DC Current Gain	$I_C = 100 \mu A, V_{CE} = 1.0 V$	100 100A	80 240		
		$I_C = 10 \text{mA}, V_{CE} = 1.0 \text{V}$	100 100A	100 300	450 600	
		$I_C = 100$ mA, $V_{CE} = 1.0$ V* $I_C = 150$ mA, $V_{CE} = 5.0$ V *	100 100A	100 100 100	350	
V _{CE(sat)}	Collector-Emitter Saturation Voltage	$I_C = 10\text{mA}, I_B = 1.0\text{mA}$ $I_C = 200\text{mA}, I_B = 20\text{mA}$			0.2 0.4	V V
V _{BE(sat)}	Base-Emitter Saturation Voltage	$I_C = 10 \text{mA}, I_B = 1.0 \text{mA}$ $I_C = 200 \text{mA}, I_B = 20 \text{mA}$			0.85 1.0	V V
Small Sign	nal Characteristics					
f _T	Current Gain Bandwidth Product	$V_{CE} = 20V, I_{C} = 20mA$		250		MHz
C _{obo}	Output Capacitance	V _{CB} = 5.0V, f = 1.0MHz			4.5	pF
NF	Noise Figure	$I_C = 100 \mu A, V_{CE} = 5.0 V$ $R_G = 2.0 k \Omega, f = 1.0 K H z$	100 100A		5.0 4.0	dB dB

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Thermal	Characteristics T _A =25°C unless otherwise noted
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		Ma			
Symbol	Parameter	PN100 PN100A	*MMBT100 *MMBT100A	Units	
P _D	Total Device Dissipation	625	350	mW	
	Derate above 25°C	5.0	2.8	mW/°C	
$R_{\theta JC}$	Thermal Resistance, Junction to Case	83.3		°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	200	357	°C/W	

^{*} Device mounted on FR-4 PCB 1.6" × 1.6" × 0.06."

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Typical Characteristics

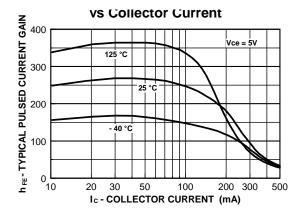


Figure 1. Typical Pulsed Current Gain vs Collector Current

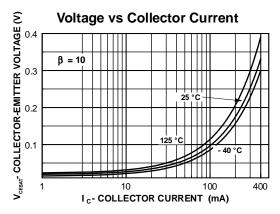


Figure 2. Collector-Emitter Saturation Voltage vs Collector Current

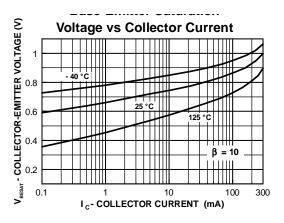


Figure 3. Base-Emitter Saturation Voltage vs Collector Current

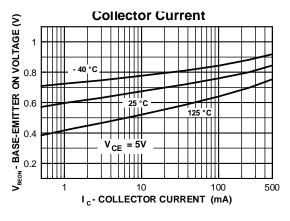


Figure 4. Base-Emitter On Voltage vs Collector Current

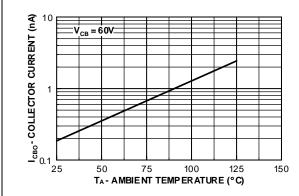


Figure 5. Collector Cutoff Current vs Ambient Temperature

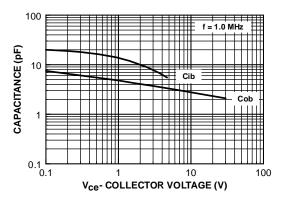


Figure 6. Input and Output Capacitance vs Reverse Voltag

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Typical Characteristics (Continued)

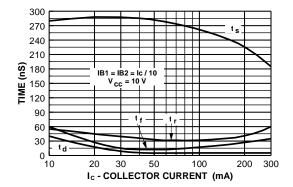


Figure 7. Switching Times vs Collector Current

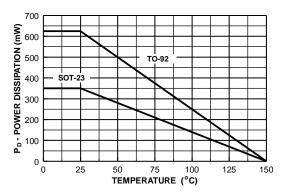
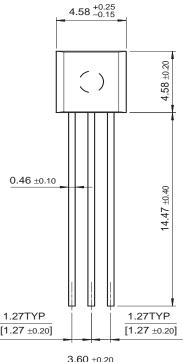


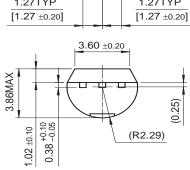
Figure 8. Power Dissipation vs Ambient Temperature

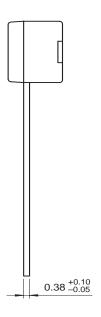
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Package Dimensions

TO-92





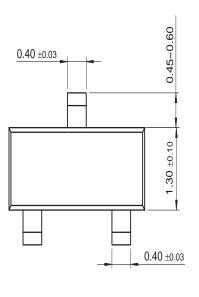


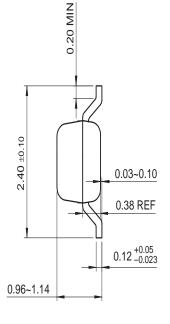
Dimensions in Millimeters

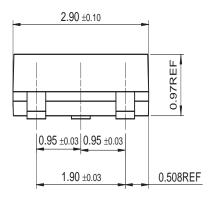
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Package Dimensions (Continued) SOT-23







Dimensions in Millimeters

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